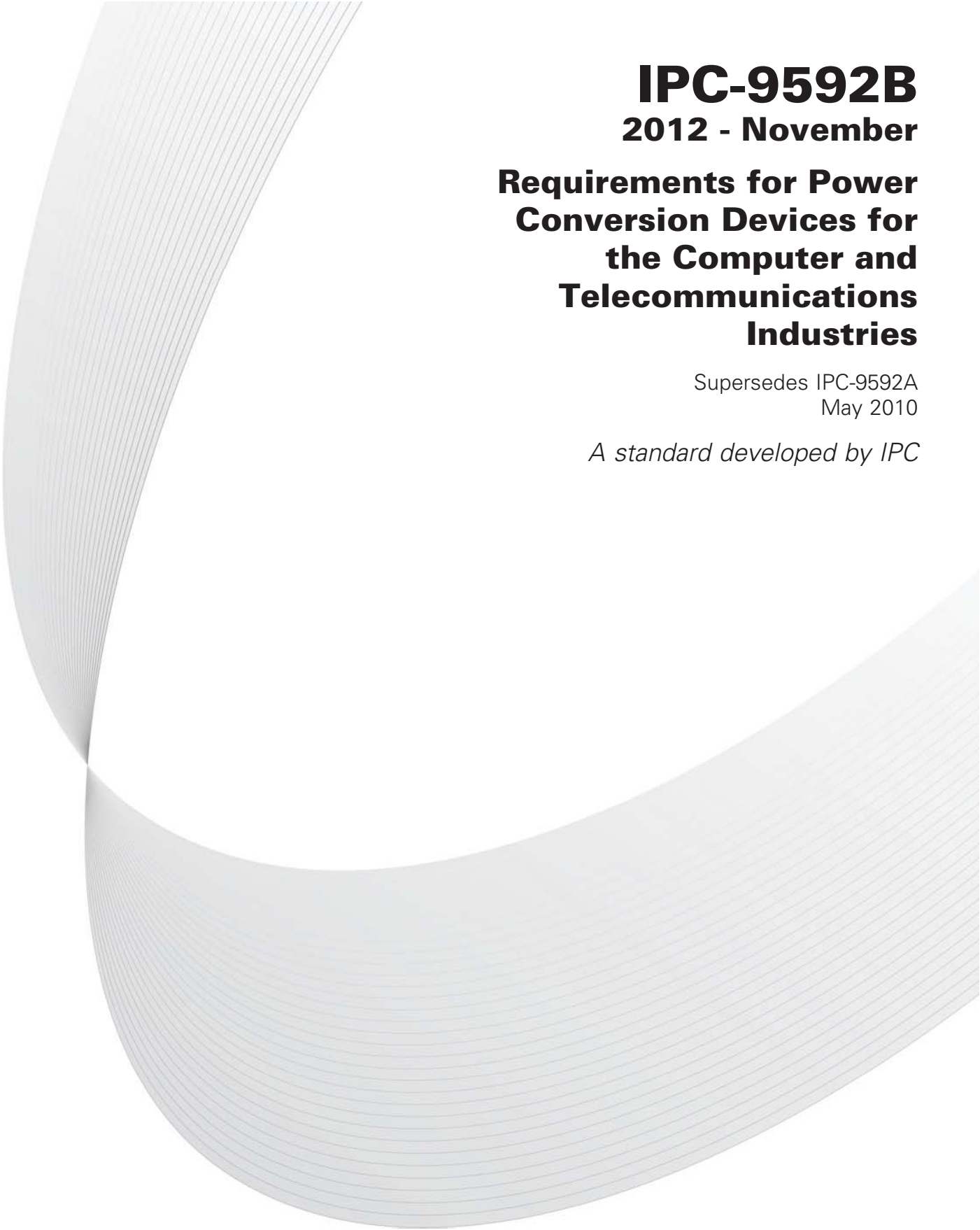




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Requirements for Power Conversion Devices for the Computer and Telecommunications Industries

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May 2010

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Association Connecting Electronics Industries



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Requirements for Power Conversion Devices for the Computer and Telecommunications Industries

Developed by the Power Conversion Devices Standard Subcommittee
(9-82) of IPC

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Users of this publication are encouraged to participate in the
development of future revisions.

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